



---

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20487ZA**

Generic Copy

---

**Issue Date:** 06-Jan-2015

**TITLE:** Final Notification of SOT-553 and SOT- 563 package/devices qualification for Assembly & Test in Leshan, China

**PROPOSED FIRST SHIP DATE:** 25-Sep-2015

**AFFECTED CHANGE CATEGORY(S):** Assembly and test site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Shero.gao@onsemi.com](mailto:Shero.gao@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

First change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor is notifying customers of the qualification and transfer the assembly and test of SOT553 and SOT563 packages from ON Semiconductor Seremban facility to ON Semiconductor Leshan facility.

The ON Semiconductor Leshan facility is certified with ISO/TS 16949:2009.

The bill of materials used in the SOT553 and SOT563 packages will remain the same between both ON Semiconductor's Seremban and Leshan's facilities.

Reliability qualification and full electrical characterization over temperature has been performed to ensure device functionality and electrical specifications are met.



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20487ZA

**Reliability Data Summary:**

**Package: SOT563**  
**Qual Vehicles: Cu Wire**

**BC847CDXV6T1G**

Test:	Conditions:	Interval:	Results
HAST+PC	Ta=130C, RH=85%, ~18.8psig, bias	96 hrs	0/156
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/156
RSH	Ta=260C, 10 sec, elec test		0/60
Solderability	Ta = 245C, 10 sec		0/30
DPA	per AEC Q101 post HAST 96 hrs		0/6

**NST3906DXV6T1G**

Test:	Conditions:	Interval:	Results
HAST+PC	Ta=130C, RH=85%, ~18.8psig, bias	96 hrs	0/78
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/78
RSH	Ta=260C, 10 sec, elec test		0/30
DPA	per AEC Q101 post HAST 96 hrs		0/4

**NSV12100XV6T1G**

Test:	Conditions:	Interval:	Results
HAST+PC	Ta=130C, RH=85%, ~18.8psig, bias	96 hrs	0/93
HTRB	Ta=150C, 80% Rated Voltage	1008 hrs	0/78
RSH	Ta=260C, 10 sec, elec test		0/30
DPA	per AEC Q101 post HAST 96 hrs		0/4

**NTZD3155CT1H**

Test:	Conditions:	Interval:	Results
Autoclave+PC	Ta=121C, RH=100%, ~15psig	96 hrs	0/84
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
HTGB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
HAST+PC	Ta=130C RH=85%, ~18.8psig, bias	96 hrs	0/89
HTSL	Ta=150C	1512 hrs	0/89
IOL	Ta=25C, delta TJ = 100C Ton=Toff = 2min	15000 cyc	0/84
TempCycle	Ta= -65/150C	2000 cyc	0/84
RSH	Ta=260C, 10 sec, elec test		0/30
Solderability	Ta = 245C, 10 sec		0/15
DPA	per AEC Q101 post TC 1K cyc		0/2
DPA	per AEC Q101 post HAST 96 hrs		0/2



**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20487ZA**

**NUF2230XV6T1G**

Test:	Conditions:	Interval:	Results
Autoclave+PC	Ta=121C, RH=100%, ~15psig	96 hrs	0/84
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
HTSL	Ta=150C	1512 hrs	0/89
IOL	Ta=25C, delta TJ = 100C Ton=Toff = 2min	15000 cyc	0/84
TempCycle	Ta= -55/150C	2000 cyc	0/84
RSH	Ta=260C, 10 sec, elec test		0/30
Solderability	Ta = 245C, 10 sec		0/15
DPA	per AEC Q101 post TC 1K cyc		0/2
DPA	per AEC Q101 post HAST 96 hrs		0/2

**NUP5120X6T1G**

Test:	Conditions:	Interval:	Results
Autoclave+PC	Ta=121C, RH=100%, ~15psig	96 hrs	0/84
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
HAST+PC	Ta=130 C RH=85%, ~18.8 psig, bias	96 hrs	0/89
HTSL	Ta=150C	1512 hrs	0/89
TempCycle	Ta= -65/150C	2000 cyc	0/84
RSH	Ta=260C, 10 sec, elec test		0/30
Solderability	Ta = 245C, 10 sec		0/15
DPA	per AEC Q101 post TC 1K cyc		0/2
DPA	per AEC Q101 post HAST 96 hrs		0/2

**NTZS3151PT1G**

Test:	Conditions:	Interval:	Results
HTRB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
HTGB	Ta=150C,80% Rated Voltage	1008 hrs	0/84
Autoclave+PC	Ta=121C, RH=100%, ~15psig	96 hrs	0/84
HAST+PC	Ta130C RH=85%, ~18.8 psig, bias	96 hrs	0/104
IOL	Ta=25C, delta TJ = 100C Ton=Toff = 2min	15000 cyc	0/84
HTSL	Ta=150C	1008 hrs	0/84
TempCycle	Ta= -65/150C	1000 cyc	0/101
RSH	Ta=260C, 10 sec, elec test		0/30
Solderability	Ta = 245C, 10 sec		0/15
DPA	per AEC Q101 post TC 1K cyc		0/2
DPA	per AEC Q101 post HAST 96 hrs		0/2



**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20487ZA**

**Package: SOT553**  
**Qual Vehicles: Au Wire**

**NL17SZ126XV5T2G**

Test:	Conditions:	Interval:	Results
HTOL	Tj=150C, Vcc=5.5V	1008 hrs	0/84
HAST+PC	Ta130C RH=85%, ~18.8 psig, bias	96 hrs	0/84
UHAST+PC	Ta130C RH=85%, ~18.8 psig, unbiased	96 hrs	0/84
HTSL	Ta=150C	1008 hrs	0/84
TempCycle	Ta= -65/150C	1000 cyc	0/84
RSH	Ta=260C, 10 sec, elec test		0/30
Solderability	Ta = 245C, 10 sec		0/15
DPA	per AEC Q101 post TC 500 cyc		0/2
DPA	per AEC Q101 post HAST 96hrs		0/5

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Available upon request

**CHANGED PART IDENTIFICATION:**

Affected products from ON semiconductor with date code 1539 representing WW39, 2015 and greater may be sourced from either the Seremban factory or the Leshan factory.

**List of affected General Parts:**

NSV12100XV6T1G	NSVBC114EPDXV6T1G	NSVT3946DXV6T1G
NSVB114YPDXV6T1G	NSVBC114YDXV6T1G	SBAS16DXV6T1G
NSVB123JPDXV6T1G	NSVBC124EDXV6T1G	SBC847BPDXV6T1G
NSVB124XPDXV6T1G	NSVEMC2DXV5T1G	SBC847CDXV6T1G
NSVB143TPDXV6T1G	NSVEMX1DXV6T1G	SNST3904DXV6T5G
NSVB143ZPDXV6T1G	NSVR0320XV6T1G	SNUF2042XV6T1G
NSVB144EPDXV6T1G	NSVT30010MXV6T1G	SZQA6V8XV5T1G
NSVBA114YDXV6T1G	NSVT3904DXV6T1G	NSVEMD4DXV6T5G
NSVBC114EDXV6T1G	NSVT3906DXV6T1G	